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## **Inventor Information for 10/749359**

Inventor Name	City	State/Country
SAUCIUC, IOAN	PHOENIX	ARIZONA
CHRYSLER, GREGORY M.	CHANDLER	ARIZONA
Appln Info Contents Petition Info	Atty/Agent Info	ontinuity/Reexam For
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1	US 7098079	20060829	Electronic assembly with	438/122	257/E23.101; 257/E23.111;	Chrysler; Gregory M.
	B2	·.	high capacity thermal interface and methods of manufacture		257/E31.131	et al.
1	US 7082031	20060725	Heatsink device and method	361/700	165/104.33; 257/E23.088;	Leija; Javier et al.
	B2		and method		257/E23.099;	ct ai.
	·				361/703; 62/259.2;	
1	Lia	20060704	IO 1:::41	257/712	62/3.2	Davis
1	US 7071552	20060704	IC die with directly bonded	257/712	257/714; 257/E23.098	Ravi; Kramadhati
	B2		liquid cooling device			V. et al.
1	US 7063268	20060620	Electro-active fluid cooling	236/93R	137/67; 236/93A;	Chrysler; Gregory M.
	B2		system		251/129.01;	et al.
					310/365; 361/699;	
				,	417/413.1; 62/259.2	
1	US 7034394	20060425	Microelectronic assembly having	257/712	257/720; 257/E21.508;	Ramanathan; Shriram et
	7034394 B2		thermoelectric		257/E21.308, 257/E23.079;	al.
	•		elements to cool a die and a		257/E23.082; 257/E27.008	:
			method of		231/E21.006	·
1	US	20060418	making the same Electronic	361/695	257/722.	Sauciuc;
1	7031155	20000418	thermal	301/093	257/722; 257/E23.099;	Ioan et al.
1	B2 US	20060404	management	415/98	361/697 361/695;	Sanchez;
1	7021891	20000 <del>4</del> 04	Micro-impeller miniature	413/70	361/693; 415/203;	Eduardo A.
	B2		centrifugal		416/183;	et al.
			compressor		416/184; 416/185	
1	US 7012011	20060314	Wafer-level	438/455	438/105	Chrysler;
	7012011 B2		diamond spreader			Gregory M. et al.
1	US	20060131	Integrated micro	257/717	257/706;	Chrysler;
	6992382 B2		channels and manifold/plenum		257/708; 257/712;	Gregory M. et al.
	·		using separate		257/713;	
			silicon or low-	L	257/714;	

			cost polycrystalline silicon		257/715; 257/716; 257/718; 257/E23.098; 361/676; 361/687; 361/689; 361/703		•
1	US 6988531 B2	20060124	Micro-chimney and thermosiphon die-level cooling	165/48.1	165/80.2; 165/905; 257/E23.087; 257/E23.088	Chrysler; Gregory M. et al.	
1	US 6981380 B2	20060103	Thermoelectric cooling for microelectronic packages and dice	62/3.2	257/E23.082; 62/259.2; 62/3.7	Chrysler; Gregory M. et al.	
1	US 6971442 B2	20051206	Method and apparatus for dissipating heat from an electronic device	165/104.25	165/104.21; 165/104.26; 165/104.33; 257/714; 257/715; 257/E23.088; 361/700	Sauciuc; Ioan et al.	
1	US 6967840 B2	20051122	Clearing of vapor lock in a microchannel cooling subsystem	361/699	165/80.4; 174/15.1; 257/714; 257/E23.098; 361/700	Chrysler; Gregory M. et al.	
1	US 6936497 B2	20050830	Method of forming electronic dies wherein each die has a layer of solid diamond	438/105	148/DIG.12; 257/E21.122; 257/E23.111; 257/E25.013; 257/E29.082; 438/459; 438/519; 438/977		
1	US 6921706 B2	20050726	Electronic assembly including a die having an integrated circuit and a layer of diamond to transfer heat	438/460	257/E21.122; 257/E21.568; 257/E23.111; 438/113	Chrysler; Gregory M. et al.	
1	US	20050712	Apparatus and	361/700	165/104.26;	Erturk;	

•							
		6917522 B1		method for cooling integrated circuit devices		165/104.33; 165/80.4; 174/15.2; 257/715; 257/E23.088; 361/695; 361/697; 361/699; 62/259.4	Hakan et al.
	1	US 6868898 B2	20050322	Heat pipe having an inner retaining wall for wicking components	165/104.26	165/185; 174/15.2; 361/700	Chau; David S. et al.
	1	US 6862183 B2	20050301	Composite fins for heat sinks	361/704	165/185; 165/80.3; 174/16.3; 257/722; 257/E23.103; 29/890.03; 361/709; 361/719	Chrysler; Gregory M. et al.
	1	US 6845622 B2	20050125	Phase-change refrigeration apparatus with thermoelectric cooling element and methods	62/3.7	165/104.21; 62/3.2	Sauciuc; Ioan et al.
	1	US 6795311 B2	20040921	Method and apparatus for cooling portable computers	361/687	361/704; 710/303; 710/304	Pokharna; Himanshu et al.
	1	US 6785134 B2	20040831	Embedded liquid pump and microchannel cooling system	361/699	165/80.4; 257/714; 257/715; 257/E23.087; 257/E23.098; 361/689; 361/698; 361/700	Maveety; James G. et al.
-	1	US 6770966 B2	20040803	Electronic assembly including a die having an integrated circuit and a layer of	257/706	257/E21.122; 257/E21.568; 257/E23.111	Chrysler; Gregory M. et al.

•							•	
[				transfer heat				
	1	US	20040316	Electronic	438/125	257/E23.101;	Mahajan;	
		6706562	1	assembly with		257/E23.111;		
		B2	1	high capacity		438/122	al.	
		1	1	thermal spreader	• .	1.20	1	
		1	1 '	and methods of		'	· '	
		1	1	manufacture		'	1	
}	1	US	20031209	Integrated vapor	361/700	165/104.26;	Prasher;	1
-	1	6661660	20051209	chamber heat	301/700	165/80.3;	Ravi et al.	
			1			165/80.4;	Ravi Ci ai.	
		B2	1	sink and spreader		· · · · · · · · · · · · · · · · · · ·	1	
		1 - 1	1	and an embedded		174/15.2;	1	
		1	1	direct heat pipe		174/16.3;	1	
		1	· '	attachment		257/714;	1	
	.	1	1			257/718;	1	
		1.	1			257/E23.088;	1	
	.	1	· '			361/702;	1	
		1	1			361/703;	1	
		1	. '	,		361/704;	1	ŀ
		1	1	· ·		361/717;	1	
		1	1			361/718;	1	
		1				361/719	1	<b> </b> .
ŀ	1	US	20031125	Electronic	257/704	257/712;	Chrysler;	1
	•	6653730	20051	assembly with		257/713;	Gregory M.	
		B2	1	high capacity		257/E23.101;	et al.	
			. '	thermal interface	,	257/E23.101, 257/E23.111	-	
ŀ	1	US	20031118	Piezoelectric	361/699	165/104.33;	Chrysler;	1
	ı	) I	20051110		301/022	165/80.4;	1 .	
		6650542 B1		actuated jet		174/15.1;	Gregory M. et al.	
		BI	1	impingement		· · · · · · · · · · · · · · · · · · ·	et ai.	
		1	1	cooling		257/714;		
		1	1			257/E23.1;		
		1	1			361/698;	†	
		<del>                                     </del>	<u> </u>			361/704	<del></del>	
	1	US	20031111	Mobile computer	361/687	62/3.2	Pokharna;	
		6646874	1.	system with			Himanshu et	
		B2	1	detachable		'	al.	
		1	1	thermoelectric		'	1.	
		1		module for		,	1	
		1 !	1	enhanced cooling	·	•		
		1 !	1	capability in a				İ
	ļ.	1	1	docking station				
Ì	1	US	20031028	Integrated vapor	361/700	165/80.4;	Prasher;	1
	•	6639799	2003.0=	chamber heat	301	174/15.2;	Ravi et al.	
		B2	1	sink and spreader		257/714;	Kavi ot al.	
		D2		and an embedded				
		1				257/715;		
i		1	1	direct heat pipe attachment		257/E23.088; 361/203;		

			•				
					361/699		• .
1	US	20031021	Composite fins	361/703	165/185;	Rinella;	
	663642	i i	for heat sinks		257/722;	Agostino C.	
	B2	.	Tor nout similar		257/E23.103;	et al.	
	102				29/890.03	Ct ai.	
	US	20030826	Tunnel-phase	165/104.33	165/104.21;	Sauciuc;	
1	660950	i i	change heat	105/104.55	165/80.4;	Ioan et al.	
	1	)1	_		174/15.2;	ioan et ai.	
	B2		exchanger		· ·		
					257/715;		
					257/E23.088;		
					361/700		
1		20030513	Heat sink and	165/185	165/80.3;	Sauciuc;	
	656126	57	electronic circuit		174/16.3;	Ioan et al.	
	B2		module including		257/722;		
			the same		257/E23.103;		
					257/E23.105;		
-					361/695;	·	
			·		361/704		
	US	20030415	Heat exchanger	361/699	165/80.4;	Sauciuc;	
	654940	7	retention		174/15.1;	Ioan et al.	
	B1	•	mechanism		257/714;		
					257/E23.094;		•
					257/E23.098;		
					257/E23.104;		
			,	٠	361/698;		
				·	361/701;		•
					361/702;	l ·	
				·	361/719		
	US	20010501	Ultra high-	165/185	165/80.3;	Chrysler;	
	62238		density, high-	100,100	174/16.3;	Gregory	
	B1		performance heat		257/722;	Martin et al.	
	D1		sink		257/E23.105;	Martin et al.	
ļ.			SHIK		29/890.03;		
					361/703		
	US	20010501	Extended air	165/104.33	165/104.26;	Chu;	
	1			103/104.33	1	Richard C.	
	62238	10	cooling with heat		257/715; 257/E23.099;		
	B1		loop for dense or		1 '	et al.	
			compact		361/700	ľ	
		•	configurations of				
			electronic				
			components	465100 =	165/22		
1		20010410	Hybrid cooling	165/80.3	165/80.4;	Chrysler;	
	621319	94	system for		257/714;	Gregory M.	
	B1		electronics		257/722;	et al.	
			module		361/696;	•	
	1		I.	i	361/697;	1	

US							
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US		<del> </del>	······	<u> </u>		62/250.2	
Cooling of electronic systems	<u> </u>	T I C	20010227	0.1.1	62/04	<del></del>	CI
B1	1	1	20010327		02/94	•	1 '
1 US		1				02/239.2	
US		BI					et al.
Color   Colo	1	TIC	20000314		62/250.2	62/196.4	Hora: Jeffrey
A	1		20000314		02/239.2	02/190.4	
US				•	·		J. et al.
Computer systems	1	<u> </u>	20000307		361/699	165/165	Chrysler
A	1	1	20000307		301/077	1	
US						•	
US		<b>1</b> .		Systems		1	
G023410	1	US	20000208	Extended cooling	361/681	<del></del>	Chu:
A	1	1		, -	-	1	
1 US   19991026   Modular refrigeration system   Modular refrigeration cooling for cooling for cooling for computer systems   Modular refrigeration cooling for computer systems   Modular refrigeration cooling for computer system   Modular refrigeration   Modular refriger				ı <del>-</del>		1	
1 US	1		19991026		62/196.4		
A	-	1	1,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,		02.12.011		
1 US			•				
S963425	1	US	19991005		361/695	165/104.33;	Chrysler;
A		5963425		and refrigeration		165/80.4;	
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System   S						62/259.2	
A   System   361/700;   et al.	1	1	19990921		165/170	1	
US		5954127		dual refrigeration	·	1	Gregory M.
1 US		A	•	system		-	et al.
System   S							
A	1		19990921	_	62/259.2	1	1 '
Cooling system for electronic components   361/700							!
1 US   19990810   Cold plate for   165/170   165/164;   Chrysler;   165/80.2   Gregory M   et al.     1 US   19990720   Enhanced air   cooling system   with attached   cooling unit   1 US   19990427   Cold plate for   dual refrigeration   S896922   A   systems   Cold plate for   165/165   165/170;   Gregory M.		A				•	et al.
US			•			361/700	· .
1         US         19990810         Cold plate for dual refrigeration systems         165/164;         Chrysler;           1         US         19990720         Enhanced air cooling system with attached cooling unit         361/695         Chrysler;           1         US         19990427         Cold plate for dual refrigeration systems         165/165         165/146; Chrysler;           1         US         19990427         Cold plate for dual refrigeration systems         165/170; Gregory M.         Gregory M.           1         US         19981020         Enhanced air         361/695         Chrysler;							
5934364         dual refrigeration systems         165/80.2         Gregory M et al.           1 US         19990720         Enhanced air cooling system with attached cooling unit         361/695         Chrysler; Gregory Martin et al.           1 US         19990427         Cold plate for dual refrigeration systems         165/146; Gregory M. Gre	1	LIC	10000010		165/170	165/164	Character
A   systems   et al.	1	l :	19990810	_	103/1/0	· · · · · · · · · · · · · · · · · · ·	1
1 US       19990720       Enhanced air cooling system with attached cooling unit       361/695       Chrysler; Gregory Martin et al.         1 US       19990427       Cold plate for dual refrigeration A systems       165/165       165/146; Gregory M. Grego				_		165/80.2	
5926368   Cooling system with attached cooling unit   Gregory Martin et al.     1 US	1		10000720	-	361/605		
A   with attached cooling unit   Martin et al.	1		17770120		301/033		
US         19990427         Cold plate for dual refrigeration systems         165/165         165/146; Gregory M. 62/259.2         Chrysler; Gregory M. 62/259.2           1 US         19981020         Enhanced air         361/695         Chrysler;							
1       US       19990427       Cold plate for dual refrigeration systems       165/146; 165/170; Gregory M. 62/259.2       Chrysler; Gregory M. 62/259.2         1       US       19981020       Enhanced air       361/695       Chrysler;		11					iviaitiii Ct ai.
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A   systems   62/259.2   et al.     1 US   19981020   Enhanced air   361/695   Chrysler;	*		1,7,70,127		100,100	•	
1 US 19981020 Enhanced air 361/695 Chrysler;			'	· -		· · · · · · · · · · · · · · · · · · ·	
	1		19981020		361/695		
		5825620		cooling system			Gregory

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		A		with attached		T -	Martin et al.
				cooling unit			
	1	US	19980602	Orientation	361/700	165/104.26;	Anderson;
		5761037		independent		165/80.4;	Timothy
		Α		evaporator		257/E23.088;	Merrill et al.
						62/259.2	
	1	US	19980602	Method of	29/890.03	257/E23.105;	Chrysler;
	ł	5758418		making an ultra		29/890.054	Gregory
		Α	-	high-density,			Martin et al.
				high-			
			,	performance heat			
	1	US	19980428	sink Method for field	454/184	361/695	Chrysler;
	1	5743794	19900720	upgrading of air	757/104	301/0/3	Gregory
		A		cooling capacity		•	Martin et al.
	1	US	19980217	Extended surface	361/704	174/16.3;	Agonafer;
	-	5719745		cooling for chip		257/722;	Dereje et al.
	ļ	Α		stack		257/E25.013;	
				applications		361/710	
	1	US	19980106	Air flow	165/121	165/80.3;	Agonafer;
		5704419		distribution in		257/E23.099;	Dereje et al.
		Α		integrated circuit		361/697	
	ļ			spot coolers	251152		
	1.	US	19970325	Enhanced flow	361/697	165/121;	Anderson;
		5615084		distributor for		165/80.3; 257/E23.099;	Timothy M. et al.
		A		integrated circuit spot coolers		361/719;	et al.
				spot coolers		415/178;	
				,		415/213.1	
	1	US	19970311	Enhanced flow	165/80.3	165/122;	Anderson;
		5609202		distributor for		165/124;	Timothy M.
		A		integrated circuit		165/126;	et al.
				spot coolers		165/185;	.
	1.					165/96;	
						174/16.3;	
		·				257/722;	
				•		257/E23.099;	
	1	US	19970311	Enhanced flow	165/80.3	361/697 165/122;	Anderson;
	1	5609201	177/0311	distributor for	103/00.3	165/122;	Timothy M.
		A		integrated circuit		165/126;	et al.
		* -		spot coolers		165/185;	1
						165/96;	
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						257/722;	
						257/E23.099;	

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•							
					<u> </u>	361/697	
	1	US 5604665 A	19970218	Multiple parallel impingement flow cooling with tuning	361/703	165/908; 257/722; 361/719	Chrysler; Gregory M. et al.
	1	US 5482113 A	19960109	Convertible heat exchanger for air or water cooling of electronic circuit components and the like	165/137	165/122; 165/157	Agonafer; Dereje et al.
	1	US 5456081 A	19951010	Thermoelectric cooling assembly with optimized fin structure for improved thermal performance and manufacturability	62/3.7	136/204; 165/185; 165/80.2; 257/E23.082; 62/259.2	Chrysler; Gregory M. et al.
	1	US 5412536 A	19950502	Local condensation control for liquid impingement two-phase cooling	361/700	165/104.26; 165/80.5; 174/15.2; 257/715; 257/E23.088	Anderson; Timothy M. et al.
	1	US 5370178 A	19941206	Convertible cooling module for air or water cooling of electronic circuit components	165/137	165/185; 165/80.3; 165/80.4; 257/E23.098; 257/E23.099; 361/697; 361/699; 361/703	Agonafer; Dereje et al.
	1	US 5303555 A	19940419	Electronics package with improved thermal management by thermoacoustic heat pumping	62/6	257/E23.094; 257/E23.099; 60/520; 62/259.2	Chrysler; Gregory M. et al.
·	1	US 4928207 A	19900522	Circuit module with direct liquid cooling by a coolant flowing between a heat	361/700	257/E23.088; 257/E23.093; 257/E23.094; 361/703	Chrysler; Gregory et al.

			producing component and the face of a piston			
1	US 4765397 A	19880823	Immersion cooled circuit module with improved fins	165/104.33	165/146; 165/80.3; 165/80.4; 165/903; 257/E23.098; 361/699; 361/703	Chrysler; Gregory M. et al.

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